

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming-Ji Dai</td> <td>07/19/2007</td> </tr> <tr> <td>Chun-Kai Liu</td> <td>07/19/2007</td> </tr> <tr> <td>Chih-Kuang Yu</td> <td>07/19/2007</td> </tr> <tr> <td>Cheng-Ta Ko</td> <td>07/19/2007</td> </tr> <tr> <td>Tsung-Chieh Cheng</td> <td>07/20/2007</td> </tr> </tbody> </table>		Name	Execution Date	Ming-Ji Dai	07/19/2007	Chun-Kai Liu	07/19/2007	Chih-Kuang Yu	07/19/2007	Cheng-Ta Ko	07/19/2007	Tsung-Chieh Cheng	07/20/2007
Name	Execution Date												
Ming-Ji Dai	07/19/2007												
Chun-Kai Liu	07/19/2007												
Chih-Kuang Yu	07/19/2007												
Cheng-Ta Ko	07/19/2007												
Tsung-Chieh Cheng	07/20/2007												
RECEIVING PARTY DATA													
Name:	Industrial Technology Research Institute												
Street Address:	No. 195, Section 4, Chung Hsing Road, Chutung,												
City:	Hsinchu												
State/Country:	TAIWAN												
PROPERTY NUMBERS Total: 1													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11956325</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11956325								
Property Type	Number												
Application Number:	11956325												
CORRESPONDENCE DATA													
Fax Number:	(949)660-0809												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone:	886223692800												
Email:	usa@jcipgroup.com.tw												
Correspondent Name:	JIANQ CHYUN INTELLECTUAL PROPERTY												
Address Line 1:	7F.-1, NO. 100, ROOSEVELT RD., SEC. 2,												
Address Line 4:	Taipei, TAIWAN 100												
ATTORNEY DOCKET NUMBER:	23237-US-PA												
NAME OF SUBMITTER:	Belinda Lee												
<p>Total Attachments: 2 source=23237assignment#page1.tif</p>													

CH \$40.00 11956325

ASSIGNMENT

WHEREAS,

- | | |
|-----------------------|------------------|
| 1. Dai, Ming-Ji | 2. Liu, Chun-Kai |
| 3. Yu, Chih-Kuang | 4. Ko, Cheng-Ta |
| 5. Cheng, Tsung-Chieh | |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **INTEGRATED PACKAGE STRUCTURE HAVING SOLAR CELL AND THERMOELECTRIC ELEMENT AND METHOD OF FABRICATING THE SAME**

Filed: Serial No.

Executed concurrently with the execution of this instrument

WHEREAS, Industrial Technology Research Institute
of No. 195, Section 4, Chung Hsing Road, Chutung, Hsinchu, Taiwan, R.O.C.

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Dai, Ming-Ji Date: 2007/07/19
Sole or First Joint Inventor: Dai, Ming-Ji

Signature: Liu, Chun-Kai Date: 2007/07/19
Second Joint Inventor (if any): Liu, Chun-Kai

Signature: Chih-Kuang Yu Date: 2007/07/19
Third Joint Inventor (if any): Yu, Chih-Kuang

Signature: Ko, Cheng-Ta Date: 2007/07/19
Fourth Joint Inventor (if any): Ko, Cheng-Ta

Signature: Cheng, Tsung-Chieh Date: 2007/07/20
Fifth Joint Inventor (if any): Cheng, Tsung-Chieh